PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
AKIHIRO AIBA	01/30/2004
TAKEO OKABE	01/30/2004
JUNNOSUKE SEKIGUCHI	01/30/2004

RECEIVING PARTY DATA

Name:	NIKKO MATERIALS COMPANY, LIMITED	
Street Address:	10-1, TORANOMON 2-CHOME	
Internal Address:	MINATO-KU	
City:	TOKYO	
State/Country:	JAPAN	
Postal Code:	105-8407	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12861161

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	OGOSH14BUSA
NAME OF SUBMITTER:	Melody Marsden

Total Attachments: 2 source=ogosh14b#page1.tif

PATENT REEL: 024872 FRAME: 0181

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PATENT REEL: 024872 FRAME: 0182

ASSIGNMENT

WHEREAS, Akihiro Aiba, Takeo Okabe and Junnosuke Sekiguchi, hereinafter referred to as ASSIGNORS, have invented and are the owners of an invention entitled COPPER ELECTROPLATING METHOD, PURE COPPER ANODE FOR COPPER ELECTROPLATING, AND SEMICONDUCTOR WAFER PLATED THEREBY WITH LITTLE PARTICLE ADHESION, said invention being fully set forth and described in the application for Letters Patent of the United States which has been prepared in connection with said invention, and which has been signed by ASSIGNORS; and

WHEREAS, NIKKO MATERIALS COMPANY, LIMITED, a Japanese corporation engaged in business at 10-1, Toranomon 2-chome, Minato-ku, Tokyo, 105-8407 Japan, hereinafter referred to as ASSIGNEE, is desirous of acquiring the said invention and any and all applications for Letters Patent and any and all Letters Patent of the United States and foreign countries which may be issued therefor;

NOW THEREFORE, THIS IS TO WITNESS, that in consideration of the sum of One Dollar (\$1.00) paid to ASSIGNORS by ASSIGNEE, the receipt of which is hereby acknowledged, and for other good and valuable consideration, ASSIGNORS have sold, assigned and set over, and hereby does sell, assign and set over, unto ASSIGNEE, its successors and assigns, the entire right, title and interest for, to and within the United States and all foreign countries, in and to the aforesaid invention and in and to any and all application for Letters Patent and Letters Patent which may be issued therefor in the United States and in any and all foreign countries.

And ASSIGNORS hereby authorize and request the Commissioner of Patent and Trademarks to issue any and all Letters patent of the United States to ASSIGNEE, its successors and assigns, as the owner of all right, title and interest therein.

And for said consideration, it is hereby covenanted and agreed that at the request and expense of ASSIGNEE, its successors and assigns, ASSIGNORS will execute any further papers and do such other acts and things as may be necessary and proper to procure Letters Patent for said invention in the United States and in such foreign countries as ASSIGNEE, its successors and assigns may elect, and vest the full title thereto in ASSIGNEE, its successors and assigns.

And ASSIGNORS hereby authorize and direct its attorneys to insert, in the space provided below, the serial number and filing date of the aforesaid application for Letters Patent of the United States when the same shall have been made known to them by the United States Patent and Trademark Office.

PATENT REEL: 024872 FRAME: 0183 IN WITNESS WHEREOF, this Assignment has been executed by us on the dates accompanying our signatures.

Apihiro Aiba	30 Jan 2004
Akihiro Aiba	(Date)
Japeo Opabre	30 Jan. 2004
Takeo Okabe	(Date)
Junnosuke Sekiguchi	30. Jan. 2004
Junnosuke Sekiguchi	(Date)

Application for United States Letters patent Serial Number 10/486,078 filed February 6, 2004

HOWSON AND HOWSON

RECORDED: 08/23/2010